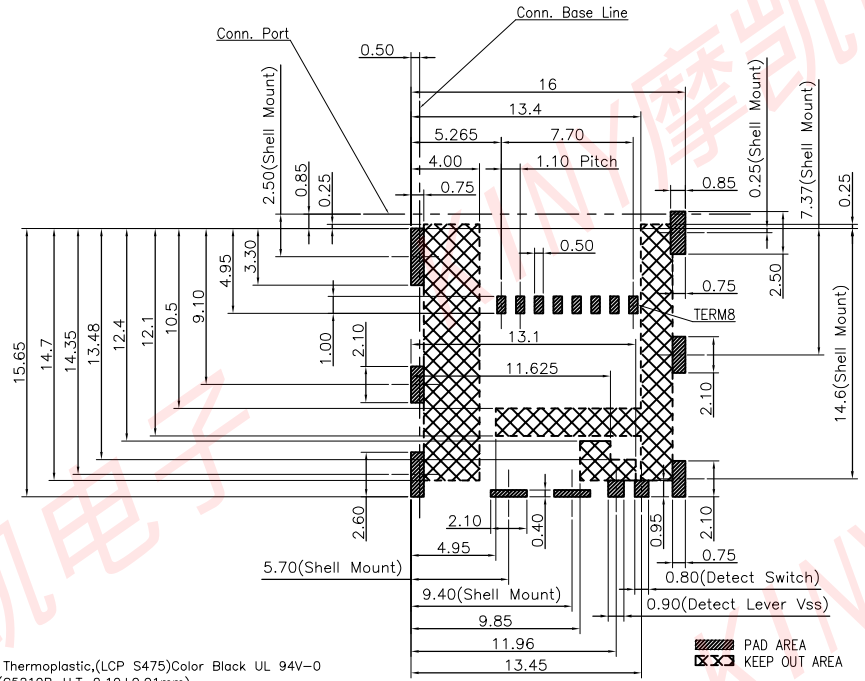
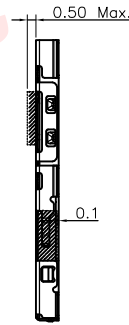
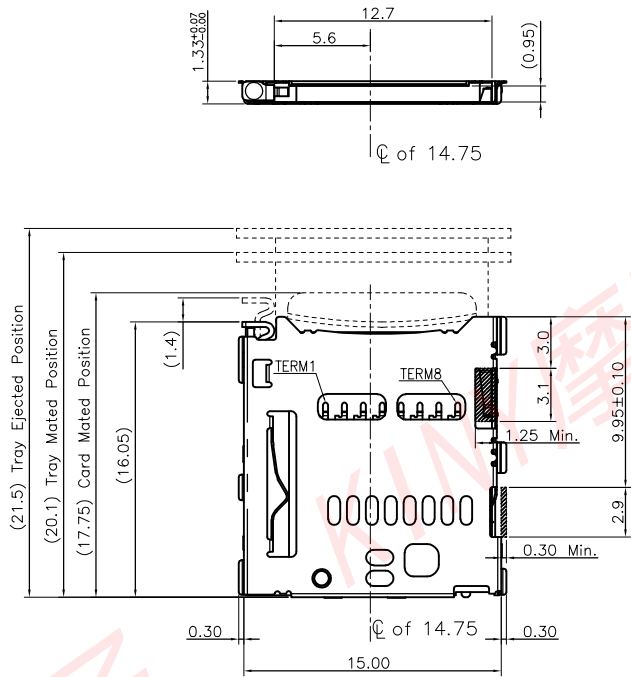


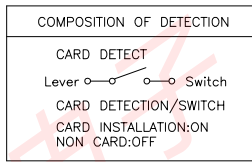
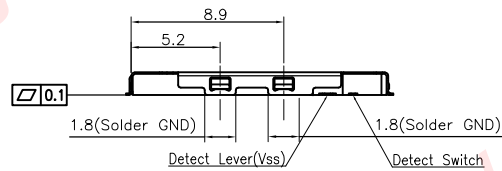
* 所有原料材质, 生产制程, 电镀必须符合HTR要求



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

NOTE:

1. Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.10±0.01mm)
 - 1-3 Cover: SUS304-H T=0.10±0.03mm
2. Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
3. Specification:
 - 3-1. Current Rating :0.5A max.
 - 3-2. Contact Resistance: 50 mOhms max
 - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5. Operating Temperature: -25°C to +85°C
 - 3-6. Mating Cycles: 5000 Insertions
4. Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT:	mm
UNLESS OTHERWISE SPECIFIABLE	
DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2'

PRODUCT NAME :	Micro SD H1.33 Topmount Pin Eject, Tray	DRAWING:	Faji	DATE:	2021.07.10
PRODUCT NO. :	MC133-T1131-01	CHECK:	Alex	DATE:	2021.07.10
DRAWING NO. :	D-MC133-T1131-01	APPROVED:	Alex	DATE:	2021.07.10
SCALE:	1:1	DWG ID:	C D	REV.:	A
				PAGE:	1 OF 1

A	INITIAL	NEW EDITION	Faji	2021.07.10
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				